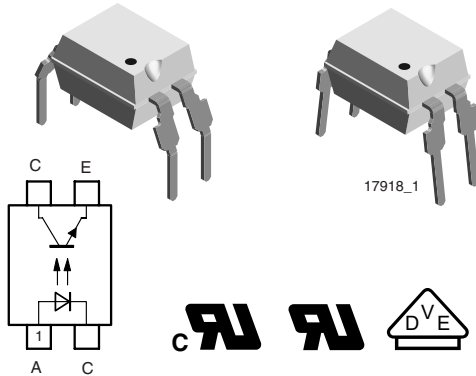


Optocoupler, Phototransistor Output, High Temperature, 110 °C Rated



DESCRIPTION

The TCET1110/ TCET1110G consists of a phototransistor optically coupled to a gallium arsenide infrared-emitting diode in a 4-pin plastic dual inline package.

The elements are mounted on one leadframe, providing a fixed distance between input and output for highest safety requirements.

VDE STANDARDS

These couplers perform safety functions according to the following equipment standards:

- **DIN EN 60747-5-2 (VDE 0884)/DIN EN 60747-5-5 pending**
Optocoupler for electrical safety requirements
- **IEC 60950**
Office machines (applied for reinforced isolation for mains voltage $\leq 400 V_{RMS}$)
- **VDE 0804**
Telecommunication apparatus and data processing
- **IEC 60065**
Safety for mains-operated electronic and related household apparatus

APPLICATIONS

- Switch-mode power supplies
- Line receiver
- Computer peripheral interface
- Microprocessor system interface
- Circuits for safe protective separation against electrical shock according to safety class II (reinforced isolation):
 - for appl. class I - IV at mains voltage $\leq 300 V$
 - for appl. class I - III at mains voltage $\leq 600 V$
 according to DIN EN 60747-5-2 (VDE 0884)/ DIN EN 60747-5-5 pending.

FEATURES

- CTR offered in 9 groups
- Isolation materials according to UL94-VO
- Pollution degree 2 (DIN/VDE 0110/resp. IEC 60664)
- Climatic classification 55/100/21 (IEC 60068 part 1)
- Special construction: therefore, extra low coupling capacity of typical 0.2 pF, high **Common Mode Rejection**
- Low temperature coefficient of CTR
- Temperature range - 40 to + 110 °C
- Rated impulse voltage (transient overvoltage) $V_{IOTM} = 8 kV_{peak}$
- Isolation test voltage (partial discharge test voltage) $V_{pd} = 1.6 kV$
- Rated isolation voltage (RMS includes DC) $V_{IOWM} = 600 V_{RMS}$
- Rated recurring peak voltage (repetitive) $V_{IORM} = 848 peak$
- Creepage current resistance according to VDE 0303/ IEC 60112 **Comparative Tracking Index: CTI ≥ 175**
- Thickness through insulation $\geq 0.75 mm$
- External creepage distance $> 8 mm$
- Lead (Pb)-free component
- Component in accordance to RoHS 2002/95/EC and WEEE 2002/96/EC


RoHS
COMPLIANT

AGENCY APPROVALS

- UL1577, file no. E76222 system code U, double protection
- BSI: EN 60065:2002, EN 60950:2000 certificate no. 7081 and 7402
- DIN EN 60747-5-2 (VDE 0884)
DIN EN 60747-5-5 pending
- FIMKO

TCET1110/TCET1110G



Vishay Semiconductors Optocoupler, Phototransistor Output,
High Temperature, 110 °C Rated

| ORDER INFORMATION | |
|-------------------|-------------------------|
| PART | REMARKS |
| TCET1110 | CTR 50 to 600 %, DIP-4 |
| TCET1111 | CTR 40 to 80 %, DIP-4 |
| TCET1112 | CTR 63 to 125 %, DIP-4 |
| TCET1113 | CTR 100 to 200 %, DIP-4 |
| TCET1114 | CTR 160 to 320 %, DIP-4 |
| TCET1115 | CTR 50 to 150 %, DIP-4 |
| TCET1116 | CTR 100 to 300 %, DIP-4 |
| TCET1117 | CTR 80 to 160 %, DIP-4 |
| TCET1118 | CTR 130 to 260 %, DIP-4 |
| TCET1119 | CTR 200 to 400 %, DIP-4 |
| TCET1110G | CTR 50 to 600 %, DIP-4 |
| TCET1111G | CTR 40 to 80 %, DIP-4 |
| TCET1112G | CTR 63 to 125 %, DIP-4 |
| TCET1113G | CTR 100 to 200 %, DIP-4 |
| TCET1114G | CTR 160 to 320 %, DIP-4 |
| TCET1115G | CTR 50 to 150 %, DIP-4 |
| TCET1116G | CTR 100 to 300 %, DIP-4 |
| TCET1117G | CTR 80 to 160 %, DIP-4 |
| TCET1118G | CTR 130 to 260 %, DIP-4 |
| TCET1119G | CTR 200 to 400 %, DIP-4 |

Note

4 Pin = single channel

G = lead form 10.16 mm; G is not marked on the body

| ABSOLUTE MAXIMUM RATINGS | | | | |
|-------------------------------------|-------------------------------|-----------|---------------|-----------|
| PARAMETER | TEST CONDITION | SYMBOL | VALUE | UNIT |
| INPUT | | | | |
| Reverse voltage | | V_R | 6 | V |
| Forward current | | I_F | 60 | mA |
| Forward surge current | $t_p \leq 10 \mu s$ | I_{FSM} | 1.5 | A |
| OUTPUT | | | | |
| Collector emitter voltage | | V_{CEO} | 70 | V |
| Emitter collector voltage | | V_{ECO} | 7 | V |
| Collector current | | I_C | 50 | mA |
| Collector peak current | $t_p/T = 0.5, t_p \leq 10 ms$ | I_{CM} | 100 | mA |
| COUPLER | | | | |
| Isolation test voltage (RMS) | $t = 1 min$ | V_{ISO} | 5000 | V_{RMS} |
| Operating ambient temperature range | | T_{amb} | - 40 to + 110 | °C |
| Storage temperature range | | T_{stg} | - 55 to + 125 | °C |
| Soldering temperature | 2 mm from case, $\leq 10 s$ | T_{sld} | 260 | °C |

Note

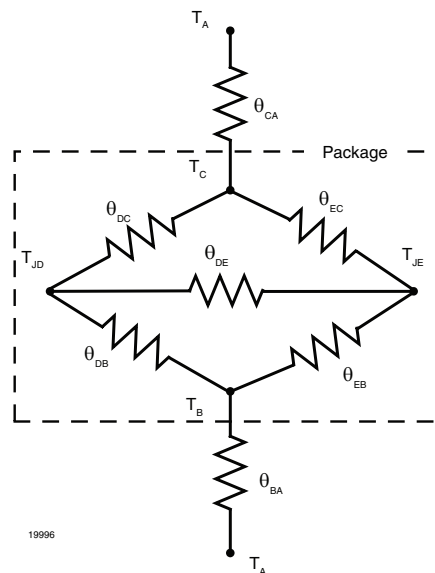
$T_{amb} = 25 \text{ }^\circ\text{C}$, unless otherwise specified.

Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. Exposure to absolute maximum ratings for extended periods of the time can adversely affect reliability.

| THERMAL CHARACTERISTICS (1) | | | | |
|---|----------------|---------------|-------|------|
| PARAMETER | TEST CONDITION | SYMBOL | VALUE | UNIT |
| LED power dissipation | at 25 °C | P_{diss} | 100 | mW |
| Output power dissipation | at 25 °C | P_{diss} | 150 | mW |
| Maximum LED junction temperature | | T_{jmax} | 125 | °C |
| Maximum output die junction temperature | | T_{jmax} | 125 | °C |
| Thermal resistance, junction emitter to board | | θ_{EB} | 173 | °C/W |
| Thermal resistance, junction emitter to case | | θ_{EC} | 149 | °C/W |
| Thermal resistance, junction detector to board | | θ_{DB} | 111 | °C/W |
| Thermal resistance, junction detector to case | | θ_{DC} | 127 | °C/W |
| Thermal resistance, junction emitter to junction detector | | θ_{ED} | 173 | °C/W |
| Thermal resistance, board to ambient ⁽²⁾ | | θ_{BA} | 197 | °C/W |
| Thermal resistance, case to ambient ⁽²⁾ | | θ_{CA} | 4041 | °C/W |

Notes

- (1) The thermal model is represented in the thermal network below. Each resistance value given in this model can be used to calculate the temperatures at each node for a given operating condition. The thermal resistance from board to ambient will be dependent on the type of PCB, layout and thickness of copper traces. For a detailed explanation of the thermal model, please reference Vishay's Thermal Characteristics of optocouplers application note.
- (2) For 2 layer FR4 board (4" x 3" x 0.062)



| ELECTRICAL CHARACTERISTICS | | | | | | |
|--------------------------------------|---|-------------|------|------|------|------|
| PARAMETER | TEST CONDITION | SYMBOL | MIN. | TYP. | MAX. | UNIT |
| INPUT | | | | | | |
| Forward voltage | $I_F = 50 \text{ mA}$ | V_F | | 1.25 | 1.6 | V |
| Junction capacitance | $V_R = 0, f = 1 \text{ MHz}$ | C_j | | 50 | | pF |
| OUTPUT | | | | | | |
| Collector emitter voltage | $I_C = 1 \text{ mA}$ | V_{CEO} | 70 | | | V |
| Emitter collector voltage | $I_E = 100 \mu\text{A}$ | V_{ECO} | 7 | | | V |
| Collector emitter cut-off current | $V_{CE} = 20 \text{ V}, I_F = 0, E = 0$ | I_{CEO} | | 10 | 100 | nA |
| COUPLER | | | | | | |
| Collector emitter saturation voltage | $I_F = 10 \text{ mA}, I_C = 1 \text{ mA}$ | V_{CEsat} | | | 0.3 | V |
| Cut-off frequency | $V_{CE} = 5 \text{ V}, I_F = 10 \text{ mA}, R_L = 100 \Omega$ | f_c | | 110 | | kHz |
| Coupling capacitance | $f = 1 \text{ MHz}$ | C_k | | 0.3 | | pF |

Note

$T_{amb} = 25 \text{ }^\circ\text{C}$, unless otherwise specified.

Minimum and maximum values are testing requirements. Typical values are characteristics of the device and are the result of engineering evaluation. Typical values are for information only and are not part of the testing requirements.

| CURRENT TRANSFER RATIO | | | | | | | |
|------------------------|---|-----------------------|--------|------|------|------|------|
| PARAMETER | TEST CONDITION | PART | SYMBOL | MIN. | TYP. | MAX. | UNIT |
| I_C/I_F | $V_{CE} = 5 \text{ V}, I_F = 1 \text{ mA}$ | TCET1111 TCET1111G | CTR | 13 | 30 | | % |
| | | TCET1112 TCET1112G | CTR | 22 | 45 | | % |
| | | TCET1113 TCET1113G | CTR | 34 | 70 | | % |
| | | TCET1114 TCET1114G | CTR | 56 | 90 | | % |
| | $V_{CE} = 5 \text{ V}, I_F = 5 \text{ mA}$ | TCET1110 TCET1110G | CTR | 50 | | 600 | % |
| | | TCET1115 TCET1115G | CTR | 50 | | 150 | % |
| | | TCET1116 TCET1116G | CTR | 100 | | 300 | % |
| | | TCET1117 TCET1117G | CTR | 80 | | 160 | % |
| | | TCET1118 TCET1118G | CTR | 130 | | 260 | % |
| | | TCET1119 TCET1119G | CTR | 200 | | 400 | % |
| | $V_{CE} = 5 \text{ V}, I_F = 10 \text{ mA}$ | TCET1111 TCET1111G | CTR | 40 | | 80 | % |
| | | TCET1112 TCET1112G | CTR | 63 | | 125 | % |
| | | TCET1113 TCET1113G | CTR | 100 | | 200 | % |
| | | TCET1114 TCET1114G | CTR | 160 | | 320 | % |



| MAXIMUM SAFETY RATINGS | | | | | | |
|------------------------|----------------|------------|------|------|------|------|
| PARAMETER | TEST CONDITION | SYMBOL | MIN. | TYP. | MAX. | UNIT |
| INPUT | | | | | | |
| Forward current | | I_F | | | 130 | mA |
| OUTPUT | | | | | | |
| Power dissipation | | P_{diss} | | | 265 | mW |
| COUPLER | | | | | | |
| Rated impulse voltage | | V_{IOTM} | | | 8 | kV |
| Safety temperature | | T_{si} | | | 150 | °C |

Note

According to DIN EN 60747-5-2 (VDE0884)/ DIN EN 60747-5-5 pending (see figure 1). This optocoupler is suitable for safe electrical isolation only within the safety ratings. Compliance with the safety ratings shall be ensured by means of suitable protective circuits.

| INSULATION RATED PARAMETERS | | | | | | |
|---|---|------------|-----------|------|------|----------|
| PARAMETER | TEST CONDITION | SYMBOL | MIN. | TYP. | MAX. | UNIT |
| Partial discharge test voltage - routine test | 100 %, $t_{test} = 1$ s | V_{pd} | 1.6 | | | kV |
| Partial discharge test voltage - lot test (sample test) | $t_{Tr} = 60$ s, $t_{test} = 10$ s, (see figure 2) | V_{IOTM} | 8 | | | kV |
| | | V_{pd} | 1.3 | | | kV |
| Insulation resistance | $V_{IO} = 500$ V | R_{IO} | 10^{12} | | | Ω |
| | $V_{IO} = 500$ V, $T_{amb} = 100$ °C | R_{IO} | 10^{11} | | | Ω |
| | $V_{IO} = 500$ V, $T_{amb} = 150$ °C (construction test only) | R_{IO} | 10^9 | | | Ω |

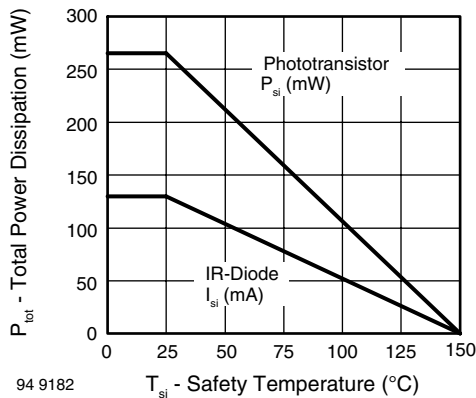


Fig. 1 - Derating Diagram

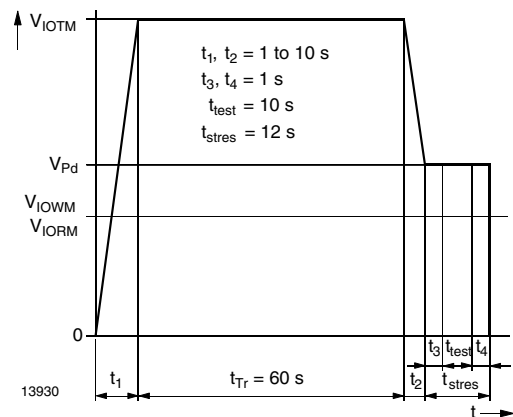


Fig. 2 - Test Pulse Diagram for Sample Test according to DIN EN 60747-5-2 (VDE 0884)/DIN EN 60747-; IEC60747

| SWITCHING CHARACTERISTICS | | | | | | |
|---------------------------|--|-----------|-----|------|-----|---------------|
| PARAMETER | TEST CONDITION | SYMBOL | MIN | TYP. | MAX | UNIT |
| Delay time | $V_S = 5\text{ V}$, $I_C = 2\text{ mA}$, $R_L = 100\ \Omega$, (see figure 3) | t_d | | 3 | | μs |
| Rise time | $V_S = 5\text{ V}$, $I_C = 2\text{ mA}$, $R_L = 100\ \Omega$, (see figure 3) | t_r | | 3 | | μs |
| Fall time | $V_S = 5\text{ V}$, $I_C = 2\text{ mA}$, $R_L = 100\ \Omega$, (see figure 3) | t_f | | 4.7 | | μs |
| Storage time | $V_S = 5\text{ V}$, $I_C = 2\text{ mA}$, $R_L = 100\ \Omega$, (see figure 3) | t_s | | 0.3 | | μs |
| Turn-on time | $V_S = 5\text{ V}$, $I_C = 2\text{ mA}$, $R_L = 100\ \Omega$, (see figure 3) | t_{on} | | 6 | | μs |
| Turn-off time | $V_S = 5\text{ V}$, $I_C = 2\text{ mA}$, $R_L = 100\ \Omega$, (see figure 3) | t_{off} | | 5 | | μs |
| Turn-on time | $V_S = 5\text{ V}$, $I_F = 10\text{ mA}$, $R_L = 1\text{ k}\Omega$, (see figure 4) | t_{on} | | 9 | | μs |
| Turn-off time | $V_S = 5\text{ V}$, $I_F = 10\text{ mA}$, $R_L = 1\text{ k}\Omega$, (see figure 4) | t_{off} | | 10 | | μs |

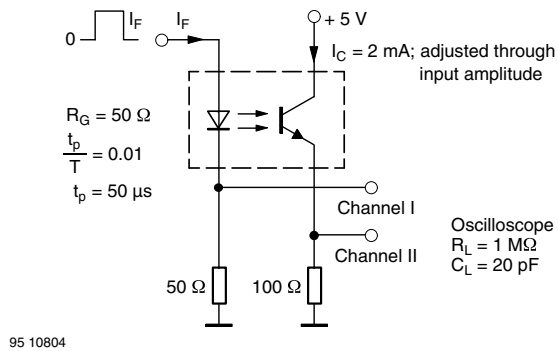


Fig. 3 - Test Circuit, Non-Saturated Operation

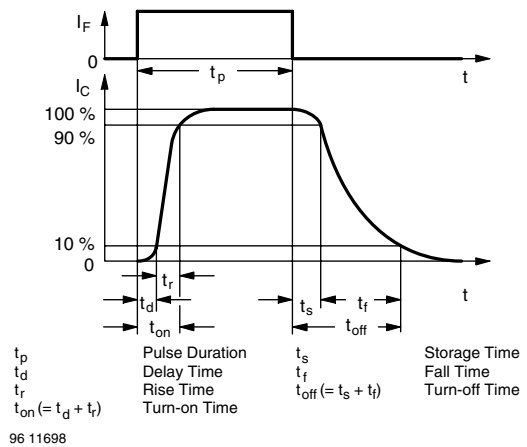


Fig. 5 - Switching Times

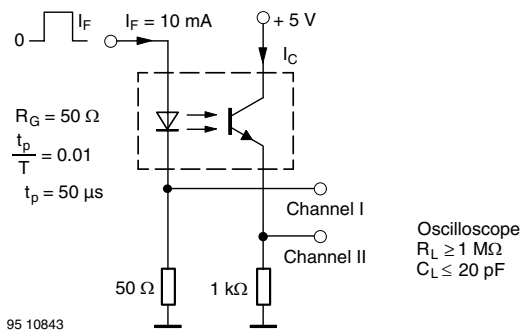


Fig. 4 - Test Circuit, Saturated Operation



TYPICAL CHARACTERISTICS

$T_{amb} = 25\text{ °C}$, unless otherwise specified

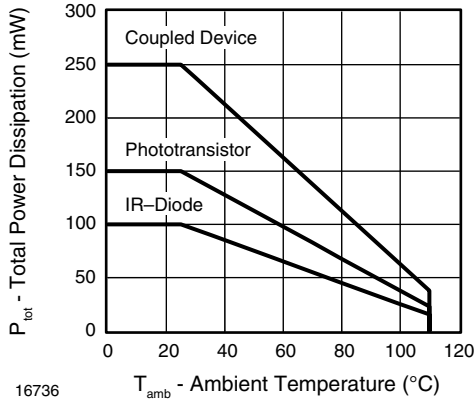


Fig. 6 - Total Power Dissipation vs. Ambient Temperature

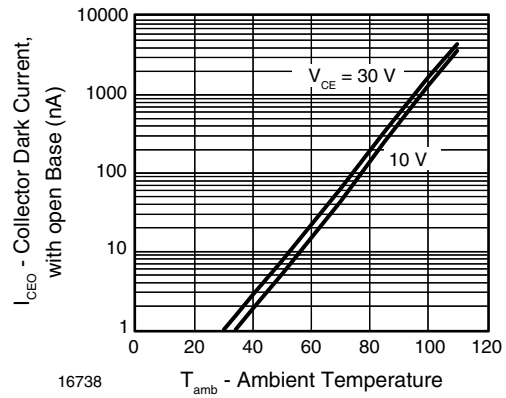


Fig. 9 - Collector Dark Current vs. Ambient Temperature

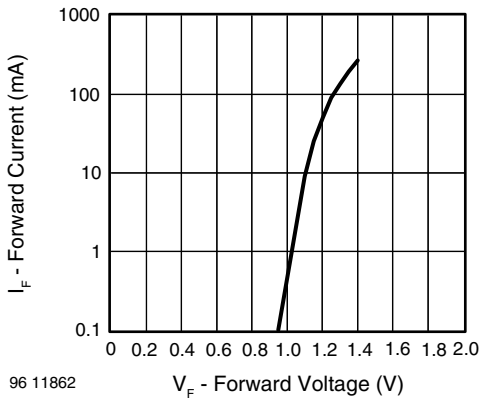


Fig. 7 - Forward Current vs. Forward Voltage

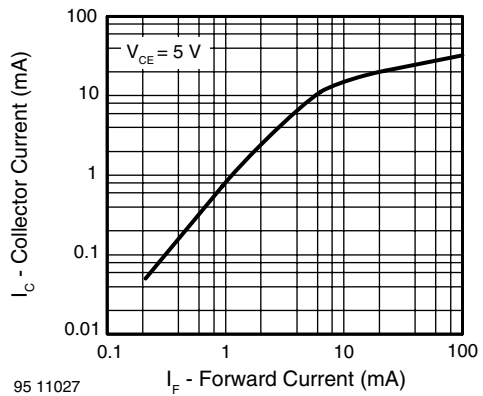


Fig. 10 - Collector Current vs. Forward Current

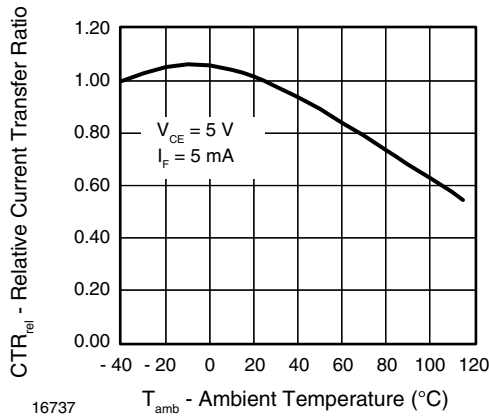


Fig. 8 - Relative Current Transfer Ratio vs. Ambient Temperature

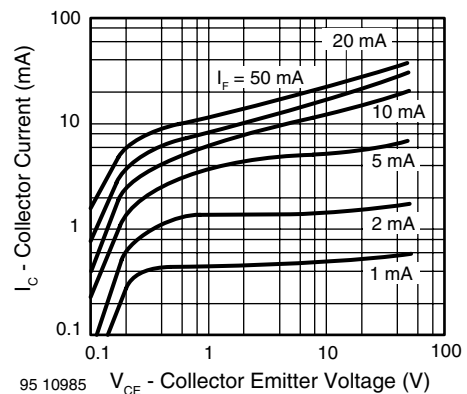


Fig. 11 - Collector Current vs. Collector Emitter Voltage

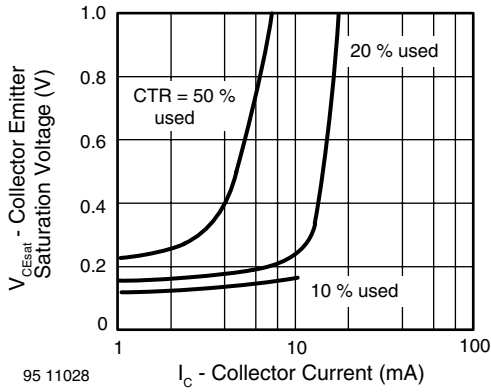


Fig. 12 - Collector Emitter Saturation Voltage vs. Collector Current

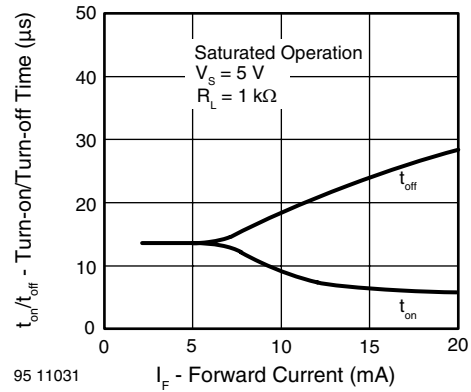


Fig. 15 - Turn-on/off Time vs. Forward Current

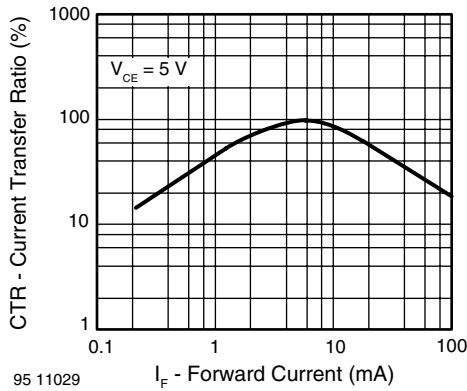


Fig. 13 - Current Transfer Ratio vs. Forward Current

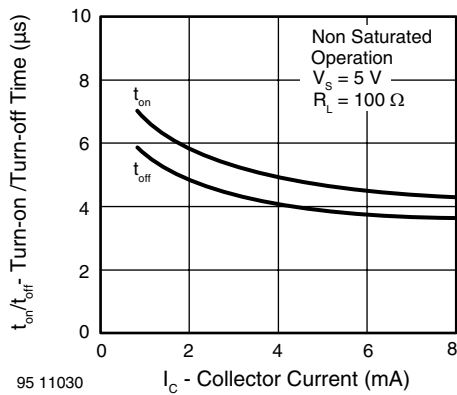


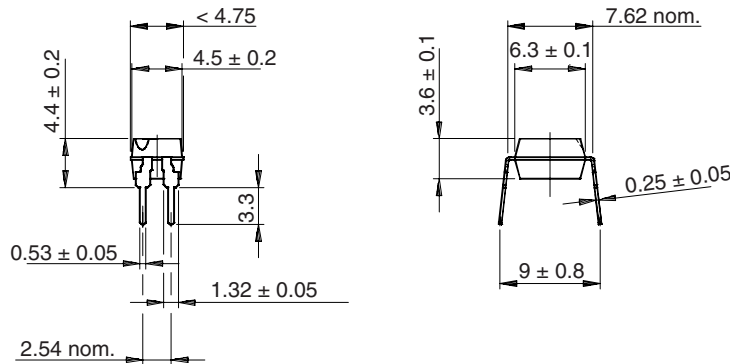
Fig. 14 - Turn-on/off Time vs. Collector Current



TCET1110/TCET1110G

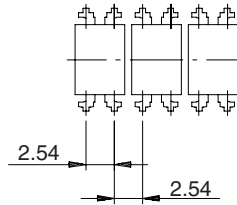
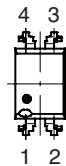
Optocoupler, Phototransistor Output, Vishay Semiconductors
High Temperature, 110 °C Rated

PACKAGE DIMENSIONS in millimeters

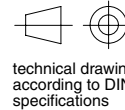


E. g.:
Special Features: Endstackable
to 2.54 mm (0.100") Spacing

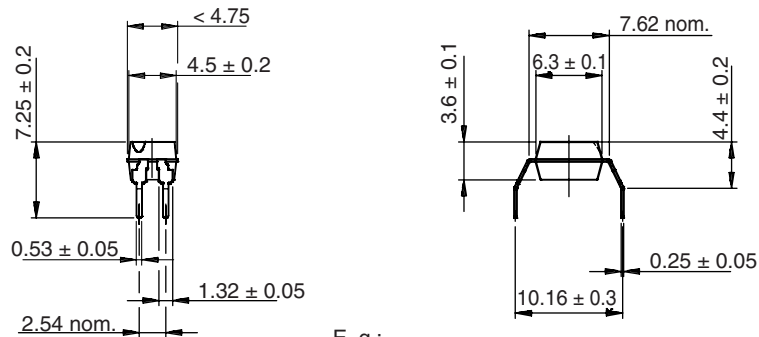
Weight: ca. 0.25 g
Creepage Distance: > 6 mm
Air Path: > 6 mm
after Mounting on PC Board



Drawing-No.: 6.544-5302.03-4
Issue: 5; 20.03.02

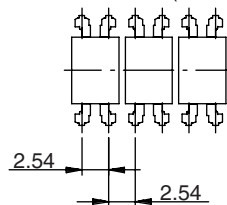
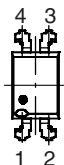


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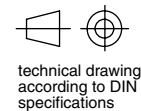


E. g.:
Special Features: Endstackable
to 2.54 mm (0.100") Spacing

Weight: ca. 0.25 g
Creepage Distance: > 8 mm
Air Path: > 8 mm
after Mounting on PC Board



Drawing-No.: 6.544-5303.03-4
Issue: 4; 20.03.02



14792

OZONE DEPLETING SUBSTANCES POLICY STATEMENT

It is the policy of Vishay Semiconductor GmbH to

1. Meet all present and future national and international statutory requirements.
2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

Vishay Semiconductor GmbH has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively.
2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

Vishay Semiconductor GmbH can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

We reserve the right to make changes to improve technical design
and may do so without further notice.

Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer. Should the buyer use Vishay Semiconductors products for any unintended or unauthorized application, the buyer shall indemnify Vishay Semiconductors against all claims, costs, damages, and expenses, arising out of, directly or indirectly, any claim of personal damage, injury or death associated with such unintended or unauthorized use.

Vishay Semiconductor GmbH, P.O.B. 3535, D-74025 Heilbronn, Germany



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Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

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